



Material Content Data Sheet



Sales Product Name	BBY 58-02V H6327			Issued		16. January 2020		
MA#	MA000765570							
Package	PG-SC79-2-1			Weight*		1.68 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	arsenic	7440-38-2	0.000	0.00		18	
	noble metal	gold	7440-57-5	0.003	0.18		1787	
	inorganic material	silicon	7440-21-3	0.026	1.53	1.71	15263	17068
leadframe	inorganic material	silicon	7440-21-3	0.000	0.01		92	
	non noble metal	titanium	7440-32-6	0.001	0.05		460	
	non noble metal	chromium	7440-47-3	0.002	0.14		1379	
	non noble metal	copper	7440-50-8	0.767	45.78	45.98	457907	459838
wire	non noble metal	copper	7440-50-8	0.007	0.41	0.41	4058	4058
encapsulation	organic material	carbon black	1333-86-4	0.007	0.43		4338	
	plastics	epoxy resin	-	0.124	7.37		73742	
	inorganic material	silicondioxide	60676-86-0	0.596	35.57	43.37	355698	433778
leadfinish	non noble metal	tin	7440-31-5	0.055	3.26	3.26	32572	32572
plating	noble metal	silver	7440-22-4	0.088	5.27	5.27	52686	52686
*deviation	< 10%	Sum in total:			100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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